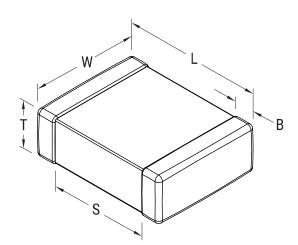


C0603C104K4RACTM

Aliases (C0603C104K4RAC7013) SMD Comm X7R, Ceramic, 0.1 uF, 10%, 16 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0603, 0.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	Yes
AEC-Q200	No
Typical Component Weight	7.3 mg
Shelf Life	78 Weeks
MSL	1

	Specifications	
0603	Capacitance	0.1 uF
1.6mm +/-0.15mm	Measurement Condition	1 kHz 1.0Vrms
0.8mm +/-0.15mm	Tolerance	10%
0.8mm +/-0.15mm	Voltage DC	16 VDC
0.5mm MIN	Dielectric Withstanding Voltage	40 VDC
0.35mm +/-0.15mm	Temperature Range	-55/+125°C
	Temp. Coefficient	X7R
	Capacitance Change with	15%, 1kHz 1.0Vrms
T&R, 180mm, Paper Tape	Reference to +25°C and 0 VDC Applied (TCC)	
4000	Dissipation Factor	3.5%1 kHz 1.0Vrms

Aging Rate

Insulation Resistance

Dimensions Chip Size

т	0.8mm +/-0.15mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

Packaging Specifications

L W

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and
we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the
requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us
with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

3% Loss/Decade Hour: Referee Time is 48 Hours

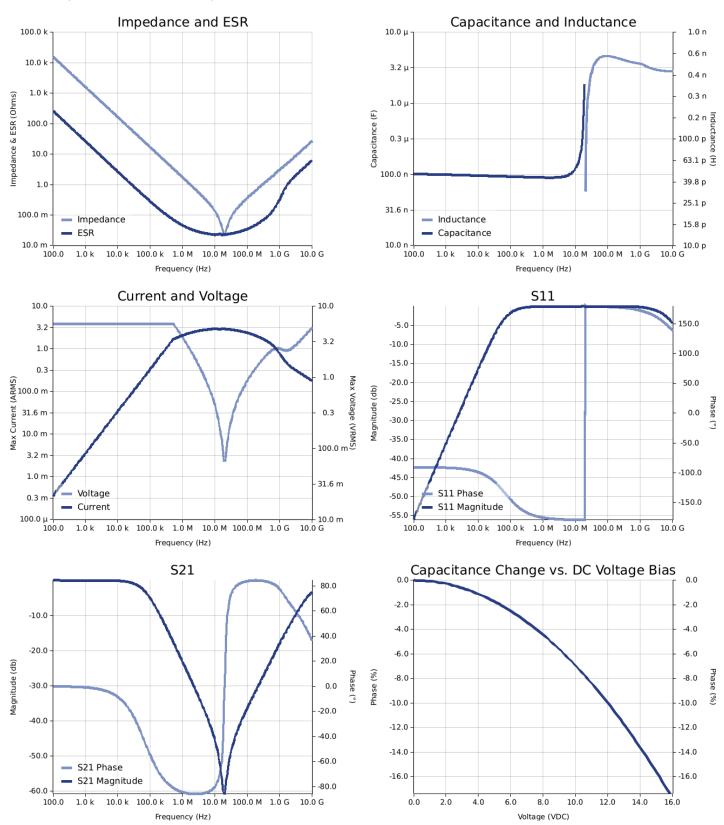
5 GOhms



CO603C104K4RACTM Aliases (C0603C104K4RAC7013) SMD Comm X7R, Ceramic, 0.1 uF, 10%, 16 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0603, 0.5 mm

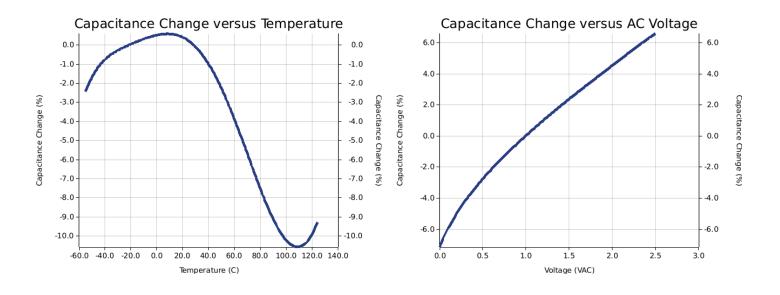
Simulations

For the complete simulation environment please visit K-SIM.





CO603C104K4RACTM Aliases (C0603C104K4RAC7013) SMD Comm X7R, Ceramic, 0.1 uF, 10%, 16 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0603, 0.5 mm





C0603C104K4RACTM

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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.